



WOM Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 59.11%	Copper (Cu)	7440-50-8	673.200	99.9790	591,008.4
	Phosphorus (P)	7723-14-0	0.007	0.0010	6.0
	Arsenic (As)	7440-38-2	0.007	0.0010	6.0
	Tin (Sn)	7440-31-5	0.007	0.0010	6.0
	Oxygen (O)	7782-44-7	0.003	0.0005	3.0
	Sulfur (S)	7704-34-9	0.082	0.0121	71.6
	Iron (Fe)	7439-89-6	0.004	0.0007	3.9
	Nickel (Ni)	7440-02-0	0.002	0.0003	1.8
	Bismuth (Bi)	7440-69-9	0.012	0.0018	10.5
	Antimony (Sb)	1309-64-4	0.012	0.0018	10.5
	Lead (Pb)	7439-92-1	0.003	0.0005	3.0
	Zinc (Zn)	7440-66-6	0.002	0.0003	1.8
	Total			673.34	
Solder Wafer 0.73%	Lead (Pb)	7439-92-1	7.78	93.29	6,833.4
	Tin (Sn)	7440-31-5	0.36	4.31	316.0
	Silver (Ag)	7440-22-4	0.20	2.40	175.6
	Total			8.34	
Chip 0.60%	Silicon (Si)	7440-21-3	6.80	100.00	5,969.8
	Total			6.80	
Case 13.70%	Epoxy	25928-94-3	156.80	100.00	137,656.1
	Total			156.80	
Potting 25.30%	Epoxy	25928-94-3	288.20	100.00	253,013.4
	Total			288.20	
Plating 0.56%	Tin (Sn)	7440-31-5	5.59	100.00	4,903.1
	Total			5.59	
Total mass (mg)			1,139.07		